REMARKS

This application is amended in a manner to place it in condition for allowance.

Status of the Claims

Claims 1, 3, and 5 have been amended as suggested in the Official Action.

Claims 7 and 8 are new. Support for claim 7 may be found, for example, at paragraphs [0031], [0044] and [0062] of the specification filed. Support for claim 8 may be found, for example, at paragraph [0075] and Table 2.

Claims 1-8 remain pending.

Claim Objections

Claims 1, 3, and 5 were objected to because of informalities.

These claims have been amended as suggested in the Official Action. Claim 1 now recites "component (D) a catalyst" and "provided that said Si-H group is introduced into the polymer". Claims 3 and 5 now recite "fine metal oxide powder".

Therefore, withdrawal of the objection is respectfully requested.

Claim Rejections-35 USC §102

Claims 1, 3, 4 and 6 were rejected under 35 USC §102(b) as being anticipated by TSUMURA et al. US 5,623,030(TSUMURA). This rejection is respectively traversed for the reasons that follow.

Independent claim 1 includes a component (A), which is a silicon containing polymer with 20% by weight or less of a component whose weight average molecular weight is 1000 or less, a component (B), which is a silicon containing polymer containing 20% by weight or less of a component whose weight average molecular weight is 1000 or less, and component (C), which is a silicon containing polymer comprising 20% by weight or less of a component whose weight average molecular weight is 1000 or less.

The silicon compounds (B) and (C) of TSUMURA, however, have a molecular weight of 1000 or less. That is, these compounds do not comprise 20% by weight or less of a component whose weight average molecular weight is 1000 or less.

Thus, TSUMURA fails to disclose or suggest the claimed components (A), (B), (C) in terms of molecular weight, as described by claim 1, as well as the molecular weight range recited in new claim 7.

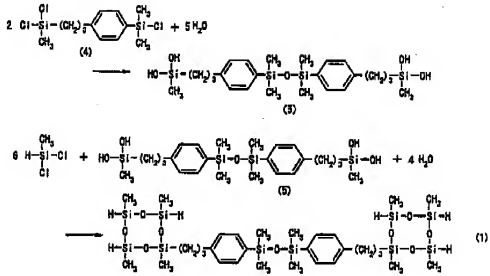
Therefore, TSUMURA fails to anticipate, or even render obvious, claims 1, 3, 4, and 6, or new claims 7 and 8, which depend from claim 1, and withdrawal of the rejection is respectfully requested.

Claims 1, 2, 4 and 6 were rejected under 35 USC §102(b) as being anticipated by FUJIKI et al. US 5,536,803(FUJIKI). This rejection is respectively traversed for the reasons that follow.

The position of the Official Action was that the fourth structure of column 12, lines 32-65 of FUJIKI corresponds to the component (C) of the claimed invention.

However, as one would have been unable to produce this structure of FUJIKI by the process of producing the components (B) and (C) of present claim 1, this fourth structure compound of FUJIKI differs from the components (B) and (C) of the present invention.

For instance, if the compound (1) below, which is among the compounds of the fourth structure of FUJIKI, is produced in accordance with the production processes of the components (B) and (C) of the present claim 1, the production process would be described as follows:



However, obtaining the intermediate (5) from compound (4) in the process noted above is hardly possible due to steric hindrance and the fact that intermediate (5) is an extremely unstable compound. Further, obtaining compound (1) by a reaction between the intermediate (5) and dichloromethylsilane is also very difficult due to steric hindrance. In view of these facts, it is not believed to be possible to produce the compound (1) by the above process.

Thus, FUJIKI fails to anticipate, or render obvious, the invention as described by claims 1, 2, 4 and 6, as well as new claims 7 and 8, which depend from claim 1.

Therefore, withdrawal of the rejection is respectfully requested.

Claims 1, 3 and 4 were rejected under 35 USC §102(b) as being anticipated by IKENO et al. US 2002/0111452(IKENO). This rejection is respectively traversed for the reasons that follow.

The silicon compound of IKENO has a viscosity of 0.001 to 1.0 Pa·s at 25 °C, preferably 0.01 to 0.1 Pa·s. However, IKENO fails to disclose or suggest each and every claimed feature, such as a 20% by weight or less of a component whose weight average molecular weight is 1000 or less.

On the contrary, the viscosity of the silicon compound of IKENO suggests a molecular weight of 1000 or less, which accordingly is different from the components (A), (B), and (C) of

the present invention in terms of molecular weight. That is, as disclosed, and as recited in new claim 8, the claimed composition, with 20% by weight or less of a component whose average molecular weight is 1000 or less, has a viscosity of 2 to 50 Pa·s at 25°C.

Moreover, as evidenced by the Comparative Examples 1 and 2 in the present specification, when a content of the component whose molecular weight is 1000 or less exceeds 20% by weight, heat resistance is greatly reduced, which is unlike the claimed invention.

Accordingly, IKENO fails to disclose or suggest the the composition as described by claims 1, 3 and 4, and new claims 7 and 8, which recite both molecular weights and viscosities greater than those suggested by IKENO.

Therefore, IKENO fails to anticipate or render obvious claims 1, 3, 4, 7 and 8, and withdrawal of the rejection is respectfully requested.

Conclusion

In view of the amendment to the claims and the foregoing remarks, this application is in condition for allowance at the time of the next Official Action. Allowance and passage to issue on that basis is respectfully requested.

Should there be any matters that need to be resolved in the present application, the Examiner is respectfully requested to contact the undersigned at the telephone number listed below.

The Commissioner is hereby authorized in this, concurrent, and future submissions, to charge any deficiency or credit any overpayment to Deposit Account No. 25-0120 for any additional fees required under 37 C.F.R. § 1.16 or under 37 C.F.R. § 1.17.

Respectfully submitted,

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